



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



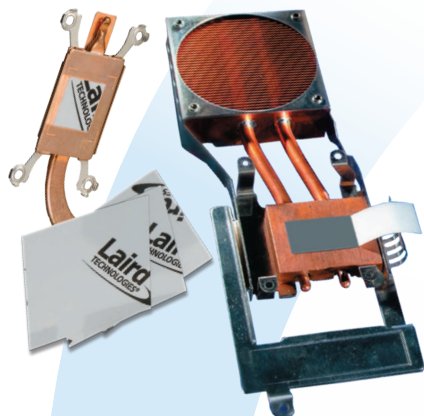
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Tpcm™ HP105 Series Phase Change Material

FOR EXCEPTIONALLY LOW THERMAL RESISTANCE

The Tpcm™ HP105 Series is a high-performance phase change material (PCM) product with exceptionally low thermal resistance.

It has a softening range of approximately 50°C to 60°C. Proprietary technology prevents excessive pump-out after the initial heat cycle. The material is naturally tacky and requires no adhesive coating or heat sink preheat for attachment.

The Tpcm HP105 Series does not cure and can be easily removed without pulling the processor out of the socket. It is supplied in rolls with a top tabbed liner for easy manual or large volume automated applications

FEATURES AND BENEFITS

- Softening range of 50°C to 60°C
- Prevents excessive pump-out after initial heat cycle
- High reliability
- Naturally tacky

APPLICATIONS

- Microprocessors
- Chipsets
- Graphic processing chips
- Custom ASICs

SPECIFICATIONS

PROPERTIES	Tpcm™ HP105	TEST METHOD
Construction & composition	Non-reinforced boron nitride filled film	
Color	Off-white	
Thickness	0.005" (0.125 mm)	
Thickness tolerance	± 0.001 (± 0.0025 mm)	
Specific gravity	1.30 g/cc	
Shelf life	1 Year	
Temperature range	-25°C to 125°C	
Phase change softening temperature	50°C to 60°C	
Optimal performance – recommend "Burn-In"	5 minutes @ 70°C or greater	
Thermal conductivity	0.73 W/mK	ATSM D5470 (modified)
Thermal Impedance °C-in ² /W (°C-cm ² /W)		
10 psi (69 Kpa)	0.024 (0.15)	ATSM D5470 (modified)
50 psi (345 Kpa)	0.017 (0.11)	
100 psi (689 Kpa)	0.015 (0.10)	
Volume resistivity	3 x 10 ¹⁴ ohm-cm	ATSM D257

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THR-DS-TPCM105 1110

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